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(12) United States Design Patent

Russo et al.

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(54) **ELECTRONICS PACKAGE**

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(**) Term: **14 Years**

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(51) **LOC (10) Cl.** **09-03**

(52) **U.S. Cl.**
USPC **D9/418**

(58) **Field of Classification Search**
USPC D9/414–419, 432, 499, 687, 517, 445; D20/15; D23/366; D13/184; 206/315.1, 320, 783; D27/189; 229/125.17; 132/229; D30/101; D28/73; D7/679; D21/311
CPC B65D 85/64; B65D 5/5038; B65D 81/36; B65D 5/14; B65D 25/10; A45D 4/16
See application file for complete search history.

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(57) **CLAIM**

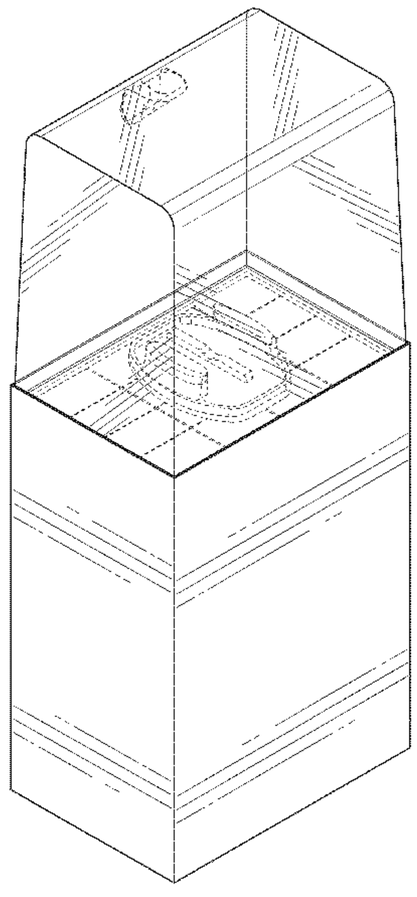
The ornamental design for an electronics package, as shown.

DESCRIPTION

FIG. **1** is a front, top and left side perspective view of an electronics package showing our new design;
FIG. **2** is a front elevational view thereof;
FIG. **3** is a rear elevational view thereof;
FIG. **4** is a right side elevational view thereof;
FIG. **5** is a left side elevational view thereof;
FIG. **6** is a top plan view thereof; and,
FIG. **7** is a bottom plan view thereof.

The broken lines in the drawings showing portions of the electronics package are included for the purpose of illustrating environmental structure and form no part of the claimed design.

1 Claim, 6 Drawing Sheets



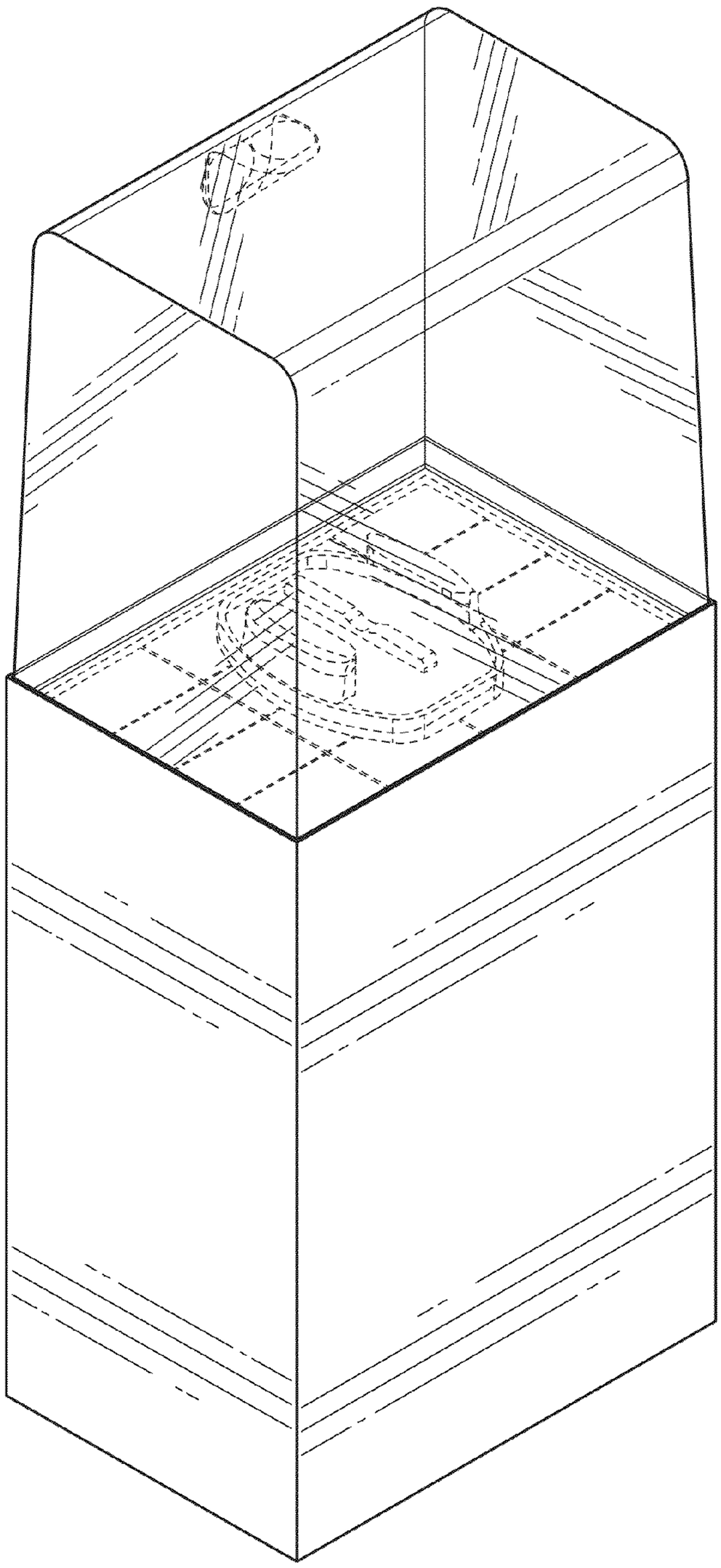


FIG. 1

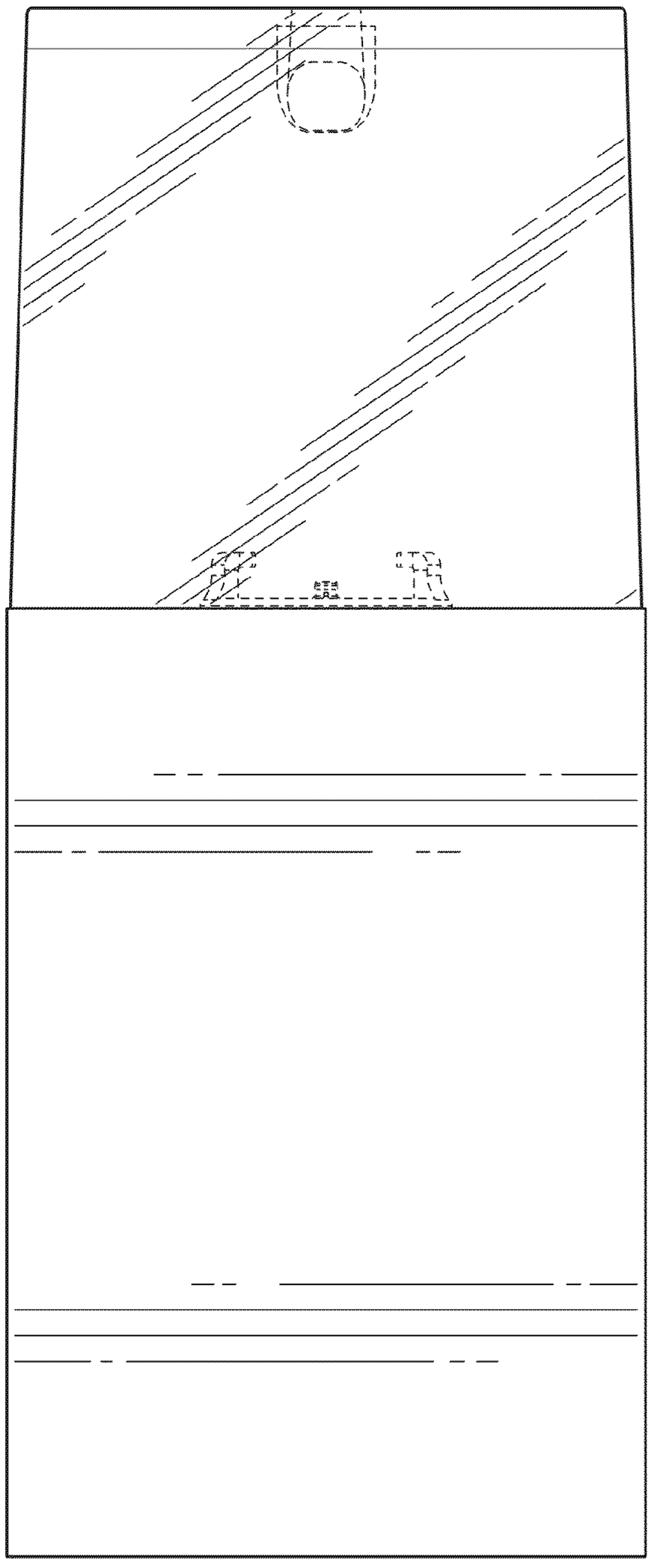


FIG. 2

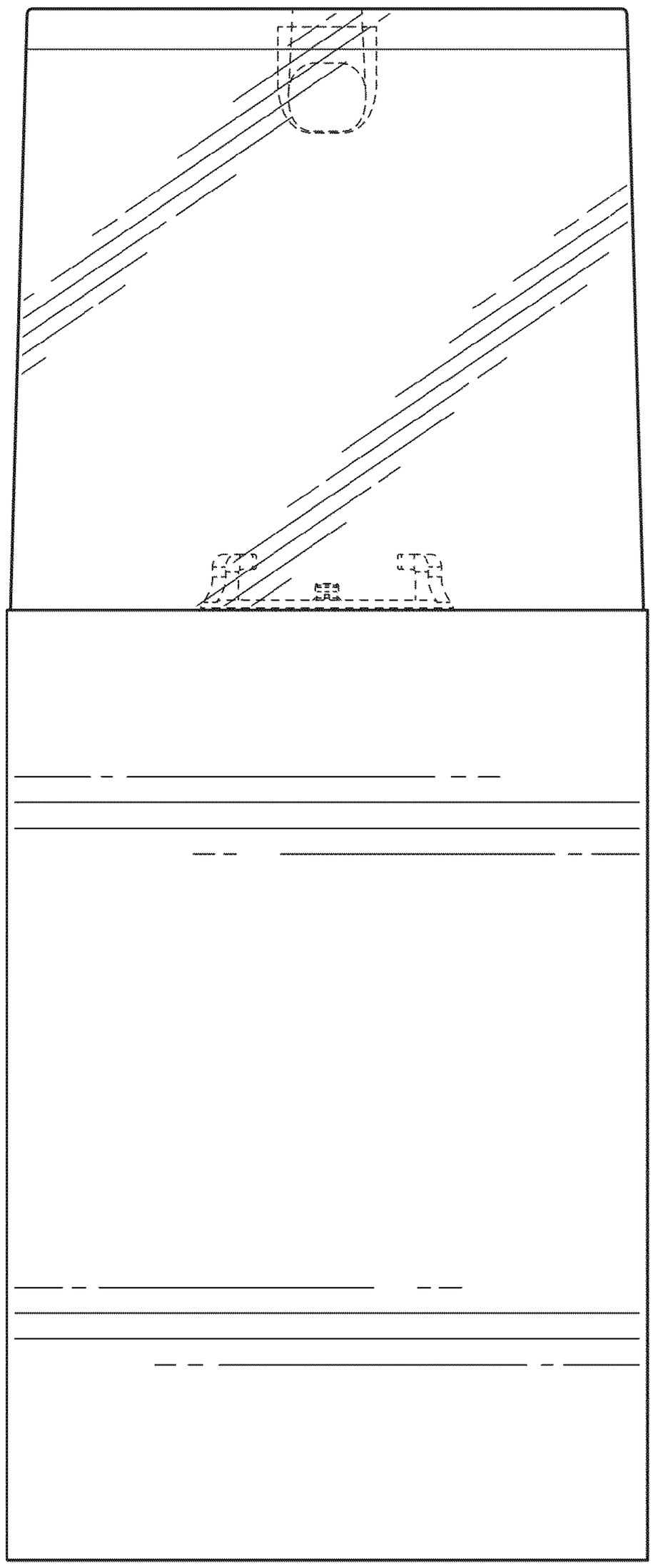


FIG. 3

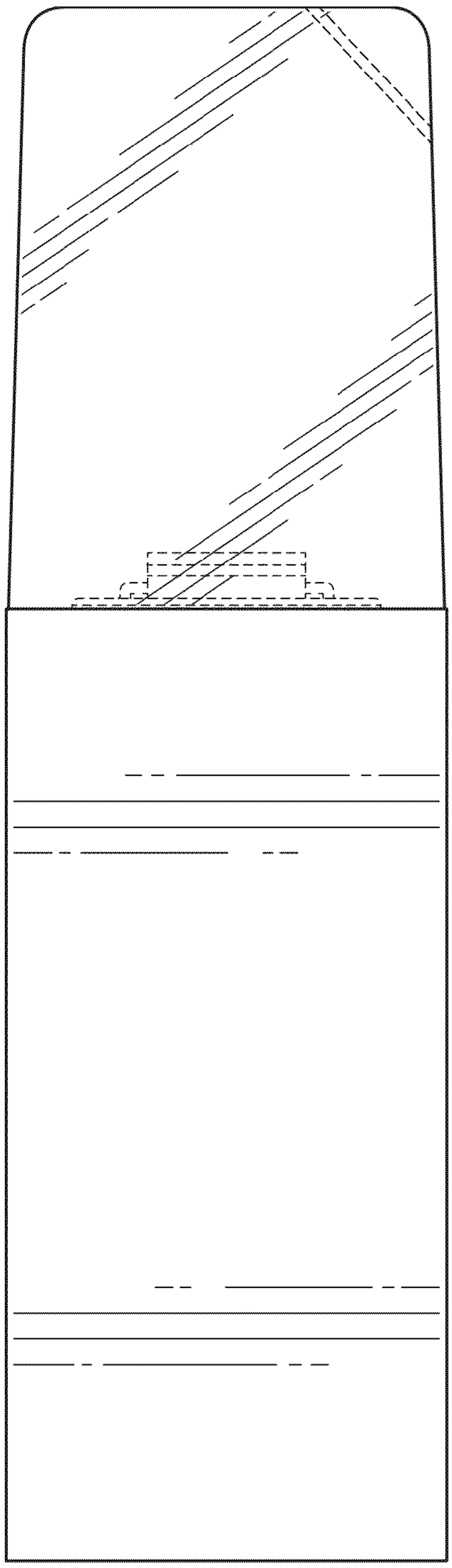


FIG. 4

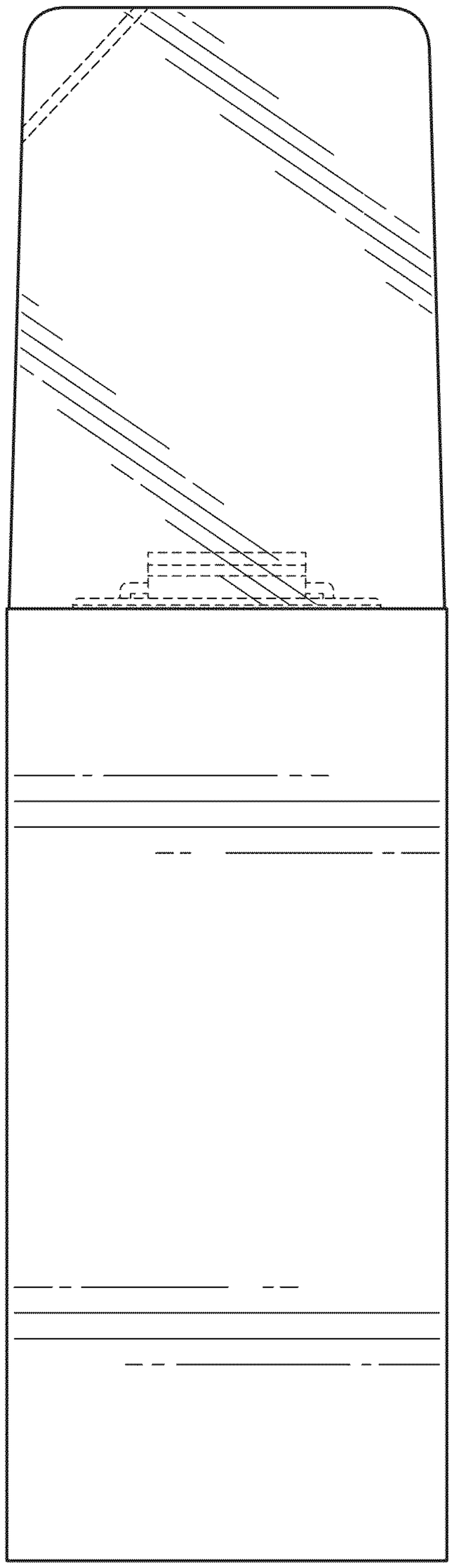


FIG. 5

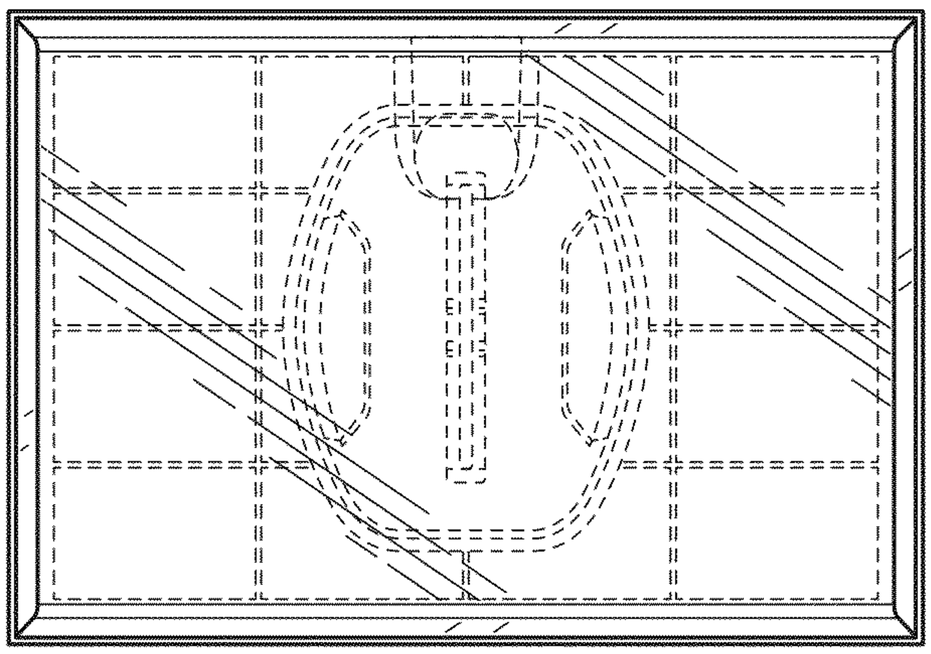


FIG. 6

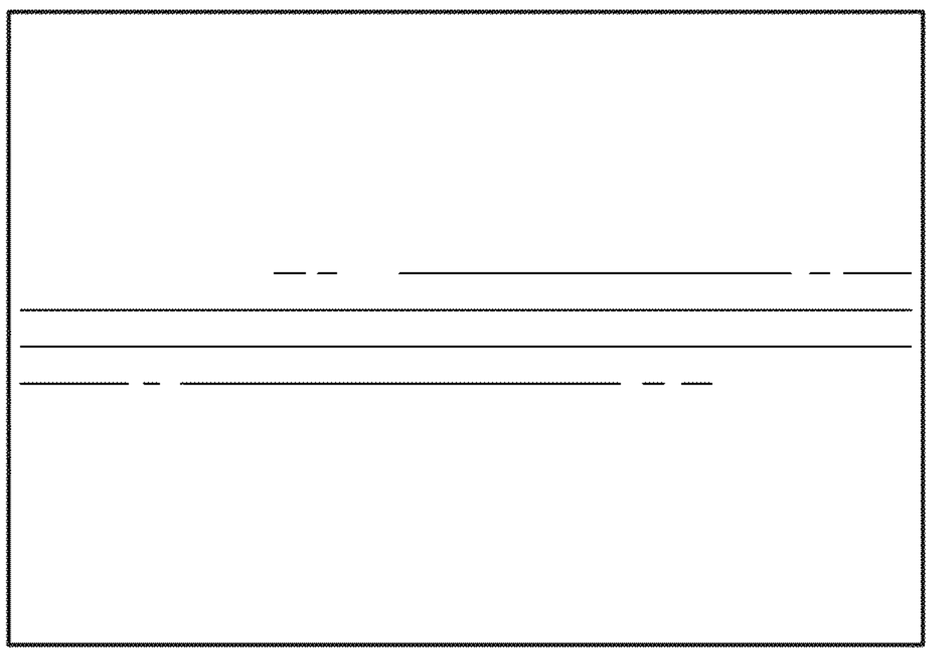


FIG. 7